

# Simplified life cycle assessment methodology

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## Life Cycle Assessment (LCA)

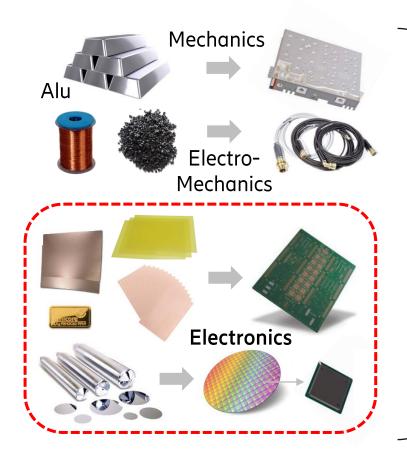
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Raw material aqusition

Production

Use (X years)

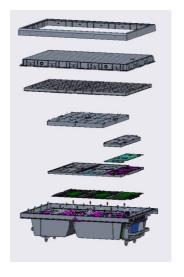
End of life treatment (EoLT)

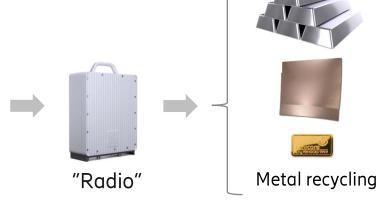






Final assembly Transports







#### LCA of an EEE product



2G-4G RAN Radio



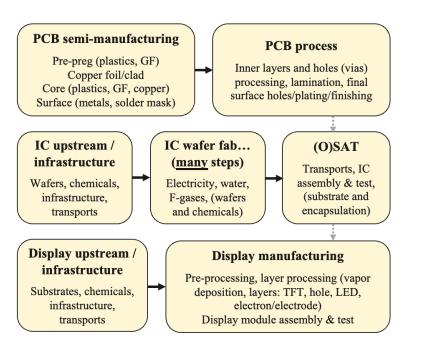
global supply chain, >>1000 components, >100 suppliers

Energy, transports, travel, and chemicals (plus infrastructure) Electricity source/mix, district heating/cooling, other energy/fuels, transport mode, travel mode, chemicals, infrastructure Infrastructure... Materials LCA (CtG) in "basic product form" Mechanics Network/Datacenter **BOM (Bill Of Materials)** operator/operation Cabinets, racks, chassis, frames, Vendor/manufacturer and "own activities" covers, fronts, mounting kits, Steel, Aluminum, Epoxy, "own activities" "nuts & bolts" Glassfiber (GF), Plastics (e.g. Network/Datacenter operation Inbound transports PE, PC) Assembly & Testing Offices, stores, etc. **Electro-Mechanics** Manganese, Zinc, Nickel. (also outsourced/EMS) Co-located network/ Chromium, Magnesium Outbound transports datacenter equip. Cables, connectors, batteries, motors/fans, climate modules, Lithium, Cobalt, Lead Support activities Network roll-out various power components (R&D, SW, M&S, (deployment), civil works, Copper, Tin, Silver, Gold, Testing & Repair) fleet vehicles Palladium Electronics 3rd party activities 3rd party activities Silicon, Gallium, Indium, Rare Earth Metals (REMs) Printed Circuit Boards (PCBs) End-of-Life treatment End-of-Life treatment Integrated Circuits (ICs) Packaging (e.g. cardboard, Device(s) operation... Displays plastics, wood) Div. "standard" components End-of-Life treatment

Collection & processing, metal recycling, residual (hazardous) waste

2 x 80 W, 18—19 kg, (150 W average) 17 kg aluminum (AI) 0.75 kg plastics/glassfiber 0.6 kg steel (Fe), 0.35 kg copper (Cu) 25 g tin/silver/gold (Sn/Ag/Au)

540 g PCB (9.3 dm²), 5.5-8 cm² IC die area



## Simplified LCA methodology



#### **Embodied emissions**

- Product parameters, PP
- Factor, f
- Emission factors, EF

Cover life cycle stages: raw material acquisition, production and End-of-life treatment (EoLT)

#### Use stage emissions

- Annual electricity consumption, AEC
- Active lifetime years, ALY
- Electricity emission factor, EEF

Total lifetime emissions = embodied emissions + use stage emissions

## Simplified LCA methodology



#### **Embodied emissions**

- Product parameters, PP
- Factor, f
- Emission factors (EF)

Simplified embodied LCA estimate
(requires an existing LCA study to create the EF)

Simplified LCA: Product Parameter Method
(no existing LCA study required, use of existing EFs)

#### Use stage emissions

- Annual electricity consumption, AEC
- Active lifetime years, ALY
- Electricity emission factor, EEF

 $AEC \times ALY \times EEF$ 

Average AEC and ALY for all products over their lifetime (not counting inactive life years before EoLT)

"The use stage for products that operates using only electricity is typically so simple the equation above covers the basic needs."





#### Simplified embodied LCA estimate

(<u>requires</u> an existing LCA study to create the EF)

#### $PP \times f \times EF$

PP = weight, volume, size, cost (most common) f = 1 in most cases PP (special cases) = % of use or based on cost

If n >1 but <10 PPs is used, it is still to be considered an embodied LCA estimate where each estimate are just added together

#### Simplified LCA: Product Parameter Method

(no existing LCA study required, use existing EFs)

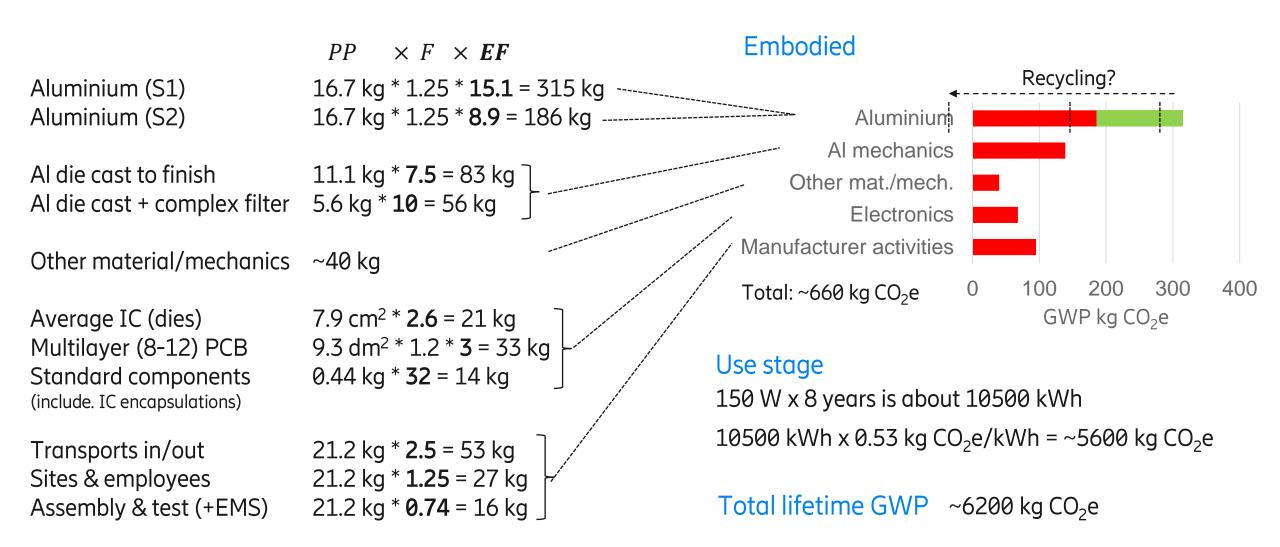
$$\sum_{n} (PPn \times fn \times EFn)$$

PP = Materials, Processes, Transports, Assembly & Test and end of life treatment (EoLT)

n >= 10 (an exact number cannot be stated)

#### Product parameter method applied on Radio

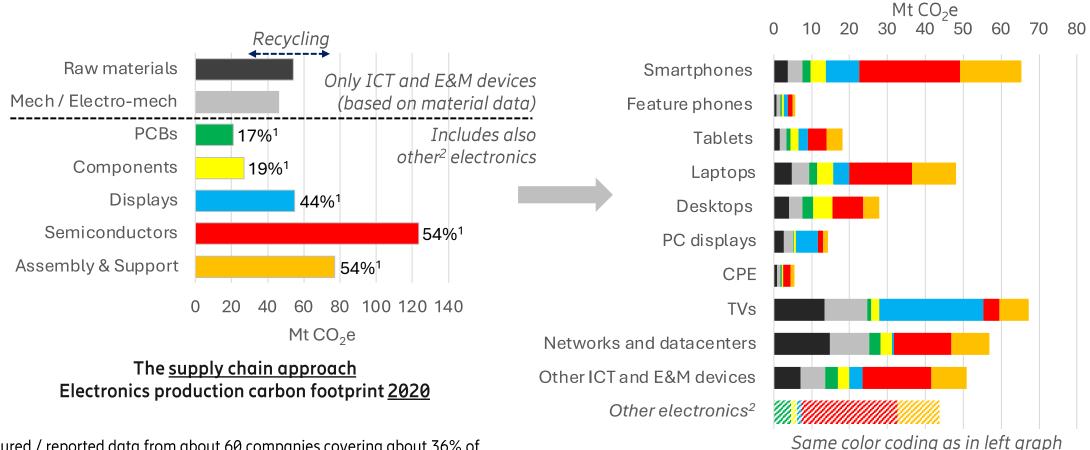




Emission factors can be created for any impact category following the same steps

#### Embodied Carbon Footprint of (ICT) Electronics





<sup>&</sup>lt;sup>1</sup> Measured / reported data from about 60 companies covering about 36% of total estimated carbon footprint (More companies have been used as references)

**Other ICT and E&M devices:** Fixed phones, STBs, Audio devices, Public and commercial displays, Smart meters, Smart home devices, Payment terminals, Surveillance cameras, Others

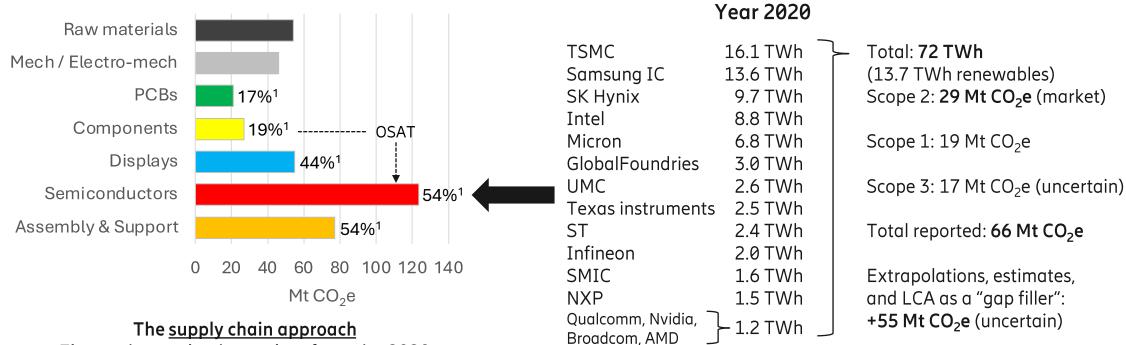
**Other electronics:** Appliances / tools, Automotive / aviation, Medical (health care), Industry (production), Government / military

E&M = Entertainment & Media sector MT = million metric ton

<sup>&</sup>lt;sup>2</sup> Not 100% of other electronics (but likely major part). It is the share that "got" included in the ICT and E&M manufacturers total data (as components and assembly/support are for all electronics).

## Supply chain approach for semiconductors (ICs)





Electronics production carbon footprint 2020

<sup>1</sup> Measured / reported data from about 60 companies covering about 36% of total estimated carbon footprint (More companies have been used as references)

Final total: 121 Mt CO<sub>2</sub>e

+OSAT: +7 = **128 Mt CO**<sub>2</sub>**e** 

OSAT = Outsourced Semiconductor Assembly & Test MT = million metric ton

## Key components



	Raw Materials	Processing (scope) Energy, process materials, infrastructure, "overhead"	
ICs	Wafer, process, encapsulation materials	Wafers → Wafer fab → (O)SAT	Low-end: 1.5 kg Memories: 2.2 kg  Average: 2.6 kg CO <sub>2</sub> e / cm <sup>2</sup> die area  Special types: 4 kg  High-end: 5 kg  Tech front: 10+ kg
PCBs	Copper, Epoxy, Glass fiber (GF), Silver/Gold	Prepreg, copper PCB processing foil, CCL, others	Basic rigid/flex (1-2 layers): 1 kg Average multilayer (<8 layers): 2.5 kg <u>Average (8-12)</u> : 3 kg CO <sub>2</sub> e / dm <sup>2</sup> PCB area Average multilayer (>12 layers): 3.5 kg HDI / IC substrate: 9 kg
Displays	Substrate, film, layer, electrode materials	Substrate/layer Display assembly & test processing	TV: 1.85 kg  Average: 2.2 kg CO <sub>2</sub> e / dm <sup>2</sup> display area PC display: 2.4 kg Laptop: 3.3 kg Tablet: 4.5 kg Smartphone: 6.8 kg

OSAT - Outsourced Semiconductor Assembly & Test HDI - High Density Interconnect

## Key challanges

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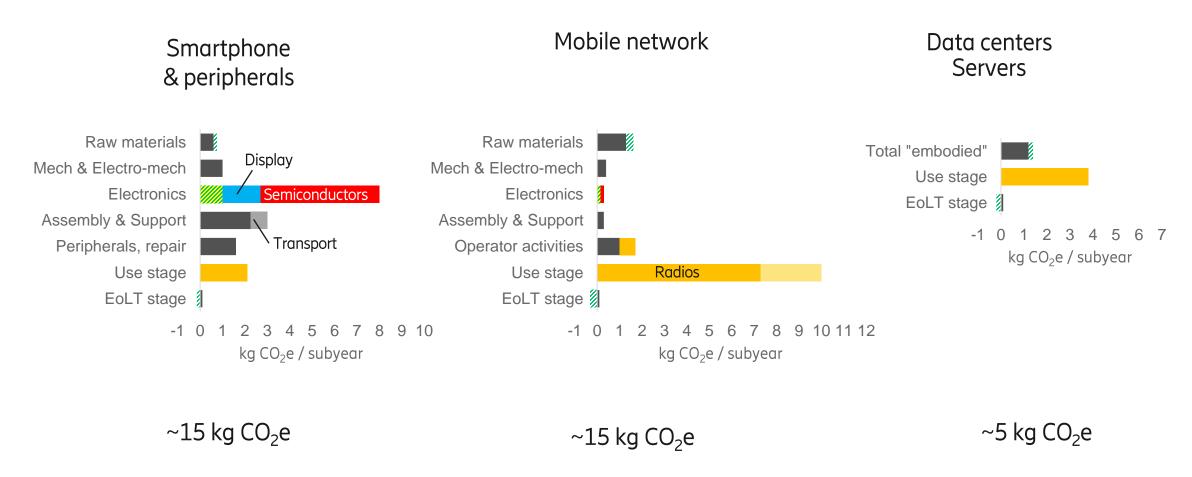
- Choose relevant materials and processes
- Collect emission factors (EF) covering the intended scope
  - Handling of upstream supply chain data
    - Known and unknown data gaps (incl. yield factors, infrastrucutre)
    - Risk of double accounting or "forgetting..."
  - Quantification of the total product output to be able to create a robust average EF
    - Product output can be sensitive information
  - Allocation of data to various types of components/products
    - Just one average do not work for all components/products

#### LCA "standard issues":

- Old generic data
- Variation in scope
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- ...<u>Uncertainty</u>

## Simplified LCA of "a mobile subscription"

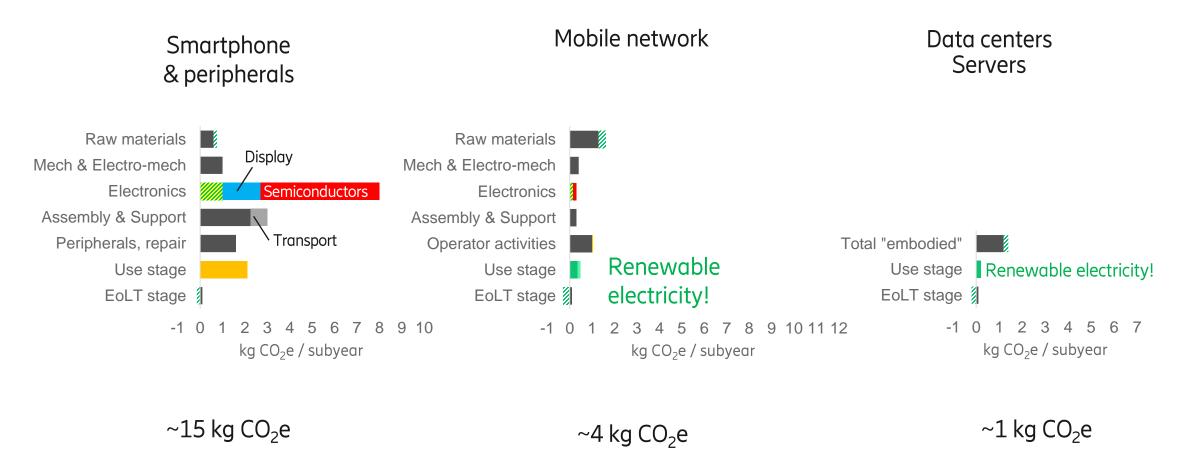




Total  $\sim$ 35 kg CO<sub>2</sub>e per subyear equals about:  $\sim$ 12 liter fuel

## Simplified LCA of "a mobile subscription"



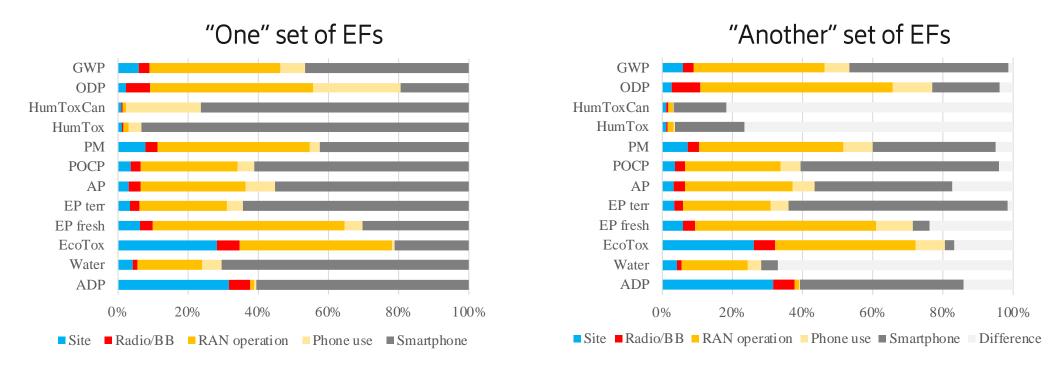


Total ~20 kg CO<sub>2</sub>e per subyear equals about: ~7 liter fuel

## A lot more impact categories...

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#### Emission factors can be created for any impact category

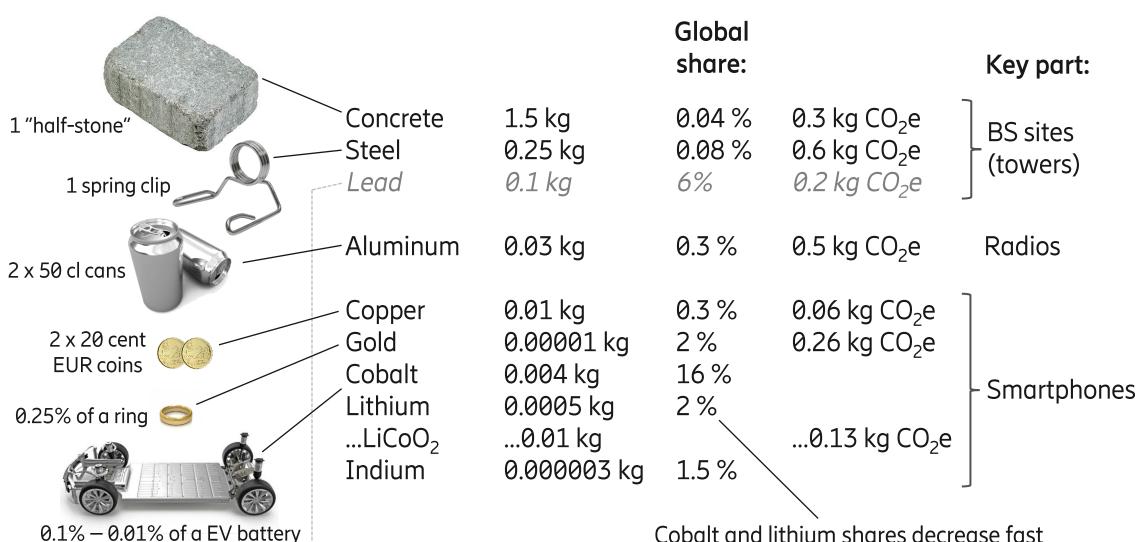


- Network operation and/or mobile phone (smartphone) manufacturing is key
- 2) Gold and copper (in the phone/smartphone) mining and processing large in Toxicities
- 3) Steel and concrete in site infrastructure is large in a few categories

## Material use per subyear

(up to 1% of a car lead battery)





Cobalt and lithium shares decrease fast due to the rapid increase of electronic vehicles batteries

